

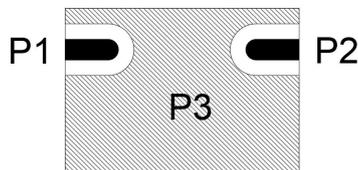
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

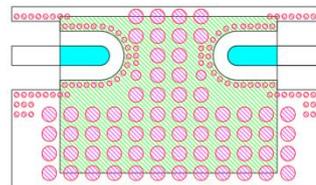
NO.	Parameter	SPC
1	Frequency range	11880-12680 MHz
2	Insertion Loss	3.7dB max. at +25°C;
3	Ripple	0.5dB @any200 MHz
4	Attenuation	60dB min. @ DC-7000MHz 50 dB min. @ 7620MHz 45 dB min. @ 9300MHz 25 dB min. @10200-11000MHz 20 dB min. @ 13600MHz 25 dB min. @ 14400MHz 45 dB min. @15200-16000MHz 50 dB min. @ 18600MHz 40 dB min. @20000-26000MHz
5	VSWR (In BW)	1.5max.
6	Group delay variation	2ns
7	Port Impedance	50Ω
8	Power	0.5W max.
9	Operation Temperature Range	-45°C ~ +85°C

Construction



PIN	Connection
1	Input port
2	Output port
3	GND

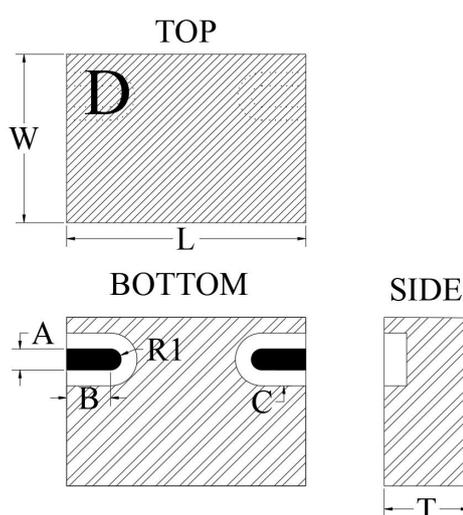
Mounting Considerations



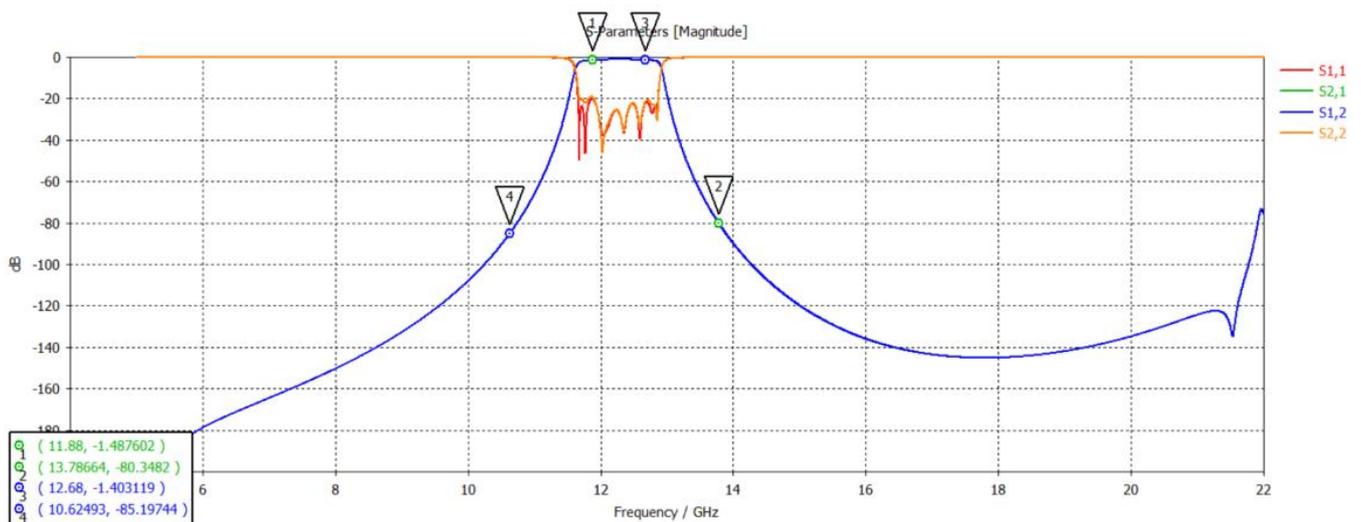
I/O 
 GND 
 Hole 

Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	4.5 ± 0.20
	W	3.2 ± 0.20
	T	1.5 ± 0.20
	A	0.4 ± 0.10
	B	0.83 ± 0.10
	C	0.3 ± 0.10
	R1	0.2 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.